Filename: PMP7156REVB_bom.xls

Date: 07/23/2012

PMP7156REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	330uF	Capacitor, Aluminum, 330µF, 850mArms	0.457 x 0.406	EEEFK1V331P	Panasonic
1	C2	220pF	Capacitor, Ceramic, 220-pF, 50-V, X7R, 15%	0603	Std	TDK
4	C3	22uF	Capacitor, Ceramic, 22-uF, 25-V, X7R, 15%	1210	GRM32ER71E226KE15L	Murata
	C4	22uF	Capacitor, Ceramic, 22-uF, 25-V, X7R, 15%	1210	GRM32ER71E226KE15L	Murata
1	C5	OPEN	Capacitor, Ceramic, (68-pF), 50-V, X7R, 15%	0603	Std	TDK
1	C6	470uF	Capacitor, Aluminum, 470µF, 850mArms	0.457 x 0.406	EEEFK1E471P	Panasonic
	C7	22uF	Capacitor, Ceramic, 22-uF, 25-V, X7R, 15%	1210	GRM32ER71E226KE15L	Murata
1	C8	100nF	Capacitor, Ceramic, 0.1-uF, 50-V, X7R, 15%	0603	Std	TDK
1	C9	3.3nF	Capacitor, Ceramic, 3300-pF, 50-V, X7R, 15%	0603	Std	TDK
1	C10	22nF	Capacitor, Ceramic, 22000-pF, 50-V, X7R, 15%	0603	Std	TDK
1	C11	470pF	Capacitor, Ceramic, 470-pF, 50-V, X7R, 15%	0603	Std	TDK
2	C12	1uF	Capacitor, Ceramic, 1-uF, 16-V, X7R, 15%	0603	Std	TDK
	C13	22uF	Capacitor, Ceramic, 22-uF, 25-V, X7R, 15%	1210	GRM32ER71E226KE15L	Murata
1	C14	6.8nF	Capacitor, Ceramic, 6800-pF, 50-V, X7R, 15%	0603	Std	TDK
	C101	1uF	Capacitor, Ceramic, 1-uF, 16-V, X7R, 15%	0603	Std	TDK
2	D1	B330-13	Diode, Schottky, 3A, 30V	SMC	B330-13	DIODES inc.
1	D2	BAS16	Diode, Switching, 150-mA, 75-V, 350mW	SOT23	BAS16	Vishay-Liteon
	D3	B330-13	Diode, Schottky, 3A, 30V	SMC	B330-13	DIODES inc.
1	D4	12V	Diode, Zener, 300mW, 12V	SOD-523	BZX585-B12	NXP
2	J1	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
	J2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	L1	33uH	Inductor, 79milliOhm, 2.5Arms, 2.9Asat	10.3 x 10.5 mm	7447714330	WE
1	Q1	BSS84	MOSFET, Pch, -50V, -0.13A, 10 Ohm	SOT23	BSS84	Infineon
1	Q2	FDC658AP	Transistor, MOSFET, Pch, -4A, -30V, 50milliohm	SuperSOT-6	FDC658AP	Fairchild
1	Q3	FDC8884	Trans, Nch, 30V, 6.5A, 23milliohm	SuperSOT-6	FDC8884	Fairchild
1	Q4	MMBTA06	Bipolar, NPN, SOT23	SOT23	MMBTA06	ON Semi
1	R1	68.1k	Resistor, Chip, 68.1K-Ohms, 1/16-W, 1%	0603	Std	Std
1	R2	0.03	Resistor, Chip, 1/8W, 1%	1206	CRCW1206-xxxx-F	Vishay
1	R3	301	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R4	1.0K	Resistor, Chip, 1k-Ohms, 1/16-W, 5%	0603	Std	Std

1	R5	5.76k	Resistor, Chip, 5.76K-Ohms, 1/16-W, 1%	0603	Std	Std
1	R7	OPEN	Resistor, Chip, (22Ohm), 1/16W, 5%	0805	Std	Std
1	R8	499	Resistor, Chip, 499-Ohms, 1/16-W, 1%	0603	Std	Std
1	R9	100K	Resistor, Chip, 100K-Ohms, 1/16-W, 1%	0603	Std	Std
1	R10	49.9	Resistor, Chip, 49.9-Ohms, 1/16-W, 1%	0603	Std	Std
1	R11	6.19k	Resistor, Chip, 6.19K-Ohms, 1/16-W, 1%	0603	Std	Std
1	TP1	5010	Test Point, Red, Thru Hole	0.125 X .0125	5010	Keystone
2	TP2	5011	Test Point, Black, Thru Hole	0.125 X .0125	5011	Keystone
4	TP3	5012	Test Point, White, Thru Hole	0.125 X .0125	5012	Keystone
	TP4	5012	Test Point, White, Thru Hole	0.125 X .0125	5012	Keystone
1	TP5	240-345	Test Point, Red, 1mm	0.038	240-345	Farnell
	TP6	5011	Test Point, Black, Thru Hole	0.125 X .0125	5011	Keystone
1	TP7	240-333	Test Point, Black, 1mm	0.038	240-333	Farnell
	TP8	5012	Test Point, White, Thru Hole	0.125 X .0125	5012	Keystone
	TP9	5012	Test Point, White, Thru Hole	0.125 X .0125	5012	Keystone
1	U1	TPS40200D	IC, Low Cost Sync Buck Controller	SO-8	TPS40200D	TI
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.					
	2. These assemblies must be clean and free from flux and all contaminants.					
	Use of no clean flux is not acceptable.					
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.					
	4. Ref designators marked with an asterisk ('**') cannot be substituted.					
	All other components can be substituted with equivalent MFG's components.					

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